

Features

The plastic package carries Underwriters Laboratory
Flammability Classification 94V-0
For surface mounted applications
Built-in strain relief, ideal for automated placement
Low forward voltage
High forward surge current capability
High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

Case : Molded plastic body

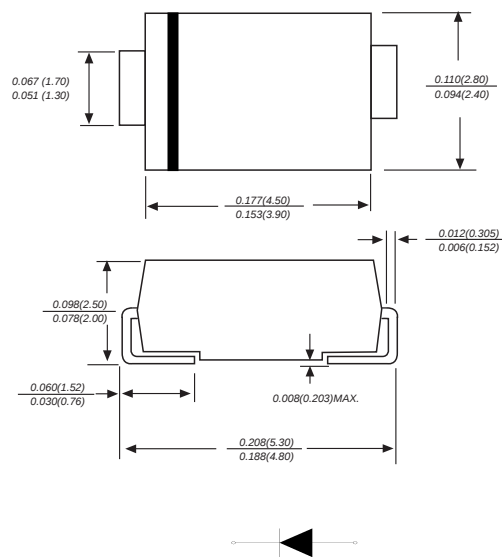
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0023 ounce, 0.07 grams

DO-214AC/SMA



Dimensions in inches and (millimeters)

Maximum Ratings (Ta=25 unless otherwise specified)

PARAMETER	SYMBOLS	VSSAF3L45-M3/6A-CN	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC blocking voltage	V_{DC}	40	V
Maximum average forward rectified current at $T_L=100^{\circ}\text{C}$	I_{AV}	3.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	80.0	A
Typical thermal resistance	R_{qJA} R_{qJL}	65 25	$^{\circ}\text{C/W}$
Operating junction temperature range	T_J	-55 to +150	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

Note: Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Electrical Characteristics (Ta=25 unless otherwise specified)

PARAMETER	SYMBOLS	TYPE	MAX	UNITS
Maximum instantaneous forward voltage at 3.0A	V_F	0.44	0.47	V
Maximum DC reverse current at rated DC blocking voltage	I_R	40 10	200 50	μA mA

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

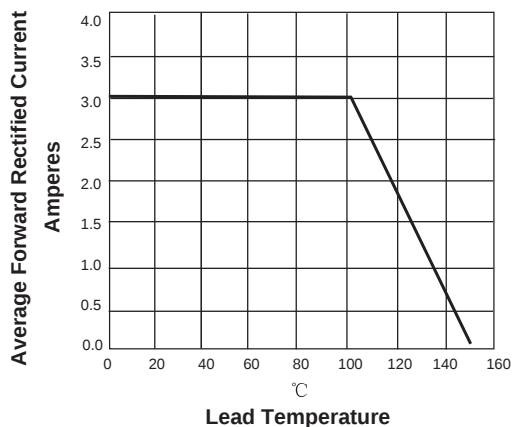


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

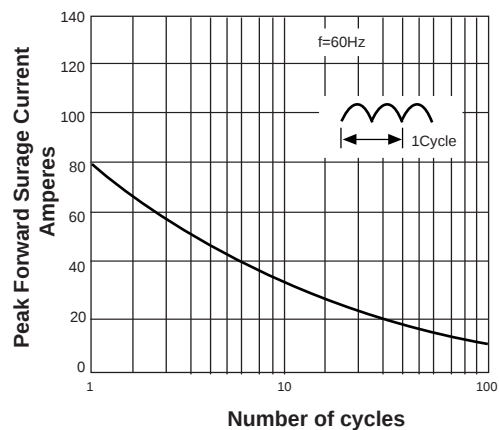


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

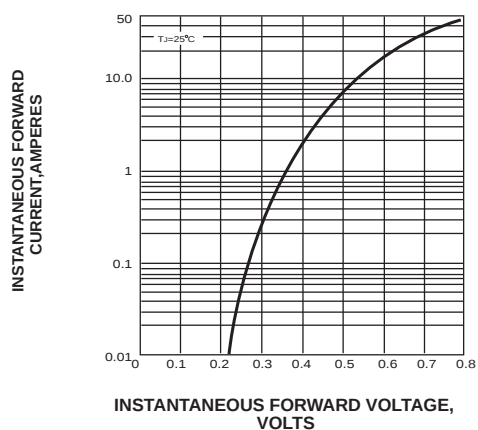
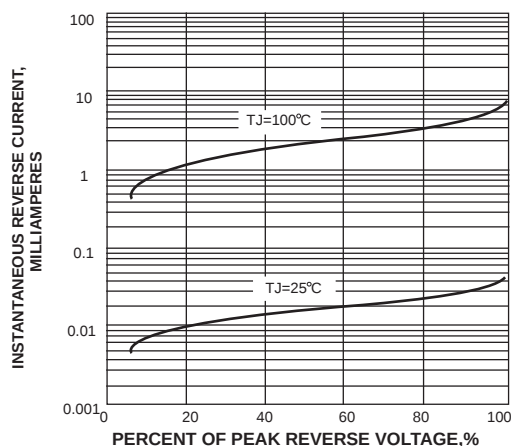
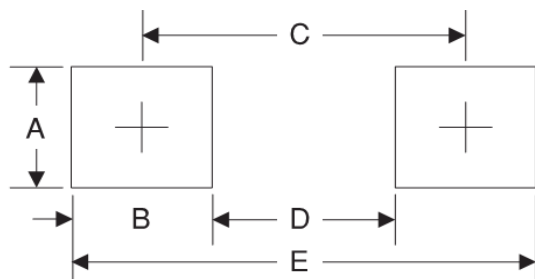


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

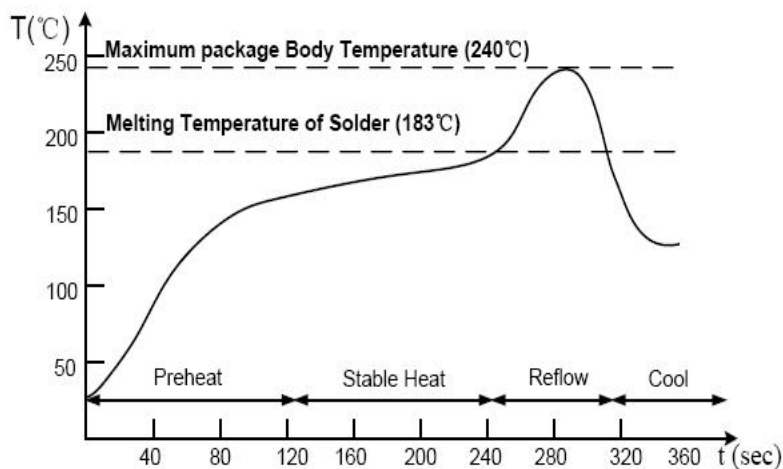


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215

Suggested Soldering Temperature Profile

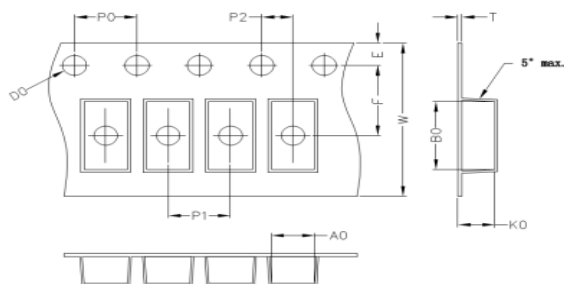


Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
 The device can be exposed to a maximum temperature of 260°C for 10 seconds.
 Devices can be cleaned using standard industry methods and solvents.
 If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.80	5.30	2.36	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMA	11'	278	5	285	10	355*310*310	80
	13'	330	7.5	340	15	360*360*360	120

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